

### Description

The IRFR024NT uses advanced trench technology

to provide excellent  $R_{\text{DS}(\text{ON})},$  low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

### **General Features**

V<sub>DS</sub> = 60V I<sub>D</sub> = 30 A

 $R_{DS(ON)} < 26m\Omega @ V_{GS}=10V$ 

### Application

Battery protection

Load switch

Uninterruptible power supply

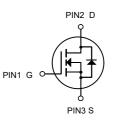
#### Package Marking and Ordering Information

0	0		
Product ID	Pack	Marking	Qty(PCS)
IRFR024NT	TO-252-2L(TO-252-2(DPAK))	30N06XXXX YYYY	2500

### Absolute Maximum Ratings (Tc=25°Cunless otherwise noted)

Symbol	Parameter Rating		Units	
Vds	Drain-Source Voltage	60	V	
Vgs	Gate-Source Voltage	±20	V	
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	30	A	
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	15	А	
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	5.6	А	
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	4.5	A	
Ідм	Pulsed Drain Current <sup>2</sup>	46	А	
EAS	Single Pulse Avalanche Energy <sup>3</sup>	25.5	mJ	
las	Avalanche Current	22.6	А	
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	34.7	W	
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>4</sup>	2	W	
Тѕтс	Storage Temperature Range	-55 to 150		
TJ	Operating Junction Temperature Range	-55 to 150		





N-Channel MOSFET



IRFR024NT

N-Channel Enhancement Mode MOSFET

R <sub>0JA</sub>	R <sub>0JA</sub> Thermal Resistance Junction-Ambient <sup>1</sup>		62	62		°C/W	
Rejc	Thermal Resistance		3.6		°	°C/W	
ectrical C	characteristics (T <sub>J</sub> =25 °C, unle	-					
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BVDSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	60			V	
∆BVbss/∆TJ	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1m/	A	0.063		V/°C	
		V <sub>GS</sub> =10V , I <sub>D</sub> =15A		22	26		
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V , I <sub>D</sub> =10A		30	38	mΩ	
VGS(th)	Gate Threshold Voltage		1.2		2.5	V	
$\bigtriangleup V_{\text{GS(th)}}$	V <sub>GS(th)</sub> Temperature Coefficient	—V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA		-5.24		mV/°(	
loss Dr		V <sub>DS</sub> =48V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°	С		1		
	Drain-Source Leakage Current	V <sub>DS</sub> =48V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°	с		5	uA	
lgss	Gate-Source Leakage Current	$V_{GS}$ = $\pm 20V$ , $V_{DS}$ = $0V$			±100	nA	
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =15A		17		S	
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		3.2		Ω	
Qg	Total Gate Charge (4.5V)			12.6			
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =48V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =12A		3.2		nC	
$Q_gd$	Gate-Drain Charge	_		6.3			
Td(on)	Turn-On Delay Time			8		- ns	
Tr	Rise Time	V <sub>DD</sub> =30V , V <sub>GS</sub> =10V ,		14.2			
Td(off)	Turn-Off Delay Time	— R <sub>G</sub> =3.3 , I <sub>D</sub> =10A		24.4			
T <sub>f</sub>	Fall Time			4.6			
Ciss	Input Capacitance			1378			
Coss	Output Capacitance		z	86		pF	
Crss	Reverse Transfer Capacitance			64			
ls	Continuous Source Current <sup>1,5</sup>				23	Α	
lsм	Pulsed Source Current <sup>2,5</sup>	$-V_G=V_D=0V$ , Force Current			46	A	
Vsd	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25°C			1.2	V	

Note :

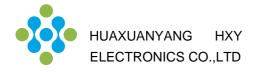
1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width  $\leqq$  300us , duty cycle  $\leqq$  2%

3. The EAS data shows Max. rating . The test condition is VDD=25V,VGS=10V,L=0.1mH,IAS=22.6A

4.The power dissipation is limited by 150°C junction temperature

5. The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.



## **Typical Characteristics**

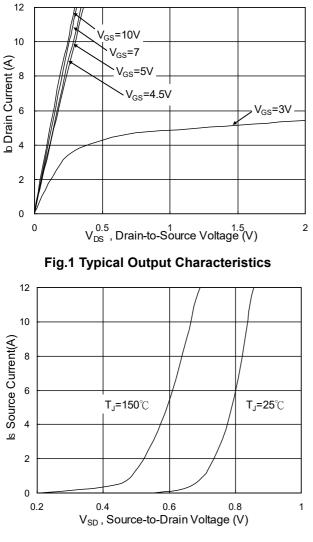


Fig.3 Forward Characteristics of Reverse

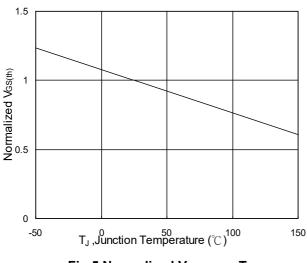


Fig.5 Normalized  $V_{GS(th)}$  v.s T<sub>J</sub>

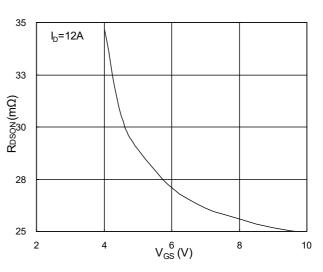


Fig.2 On-Resistance v.s Gate-Source

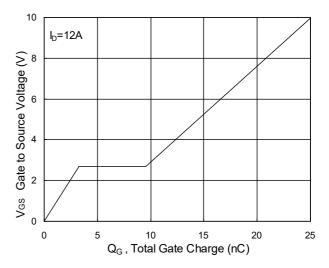


Fig.4 Gate-Charge Characteristics

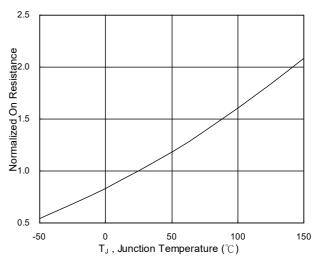
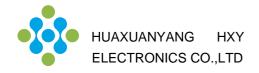


Fig.6 Normalized R<sub>DSON</sub> v.s T<sub>J</sub>



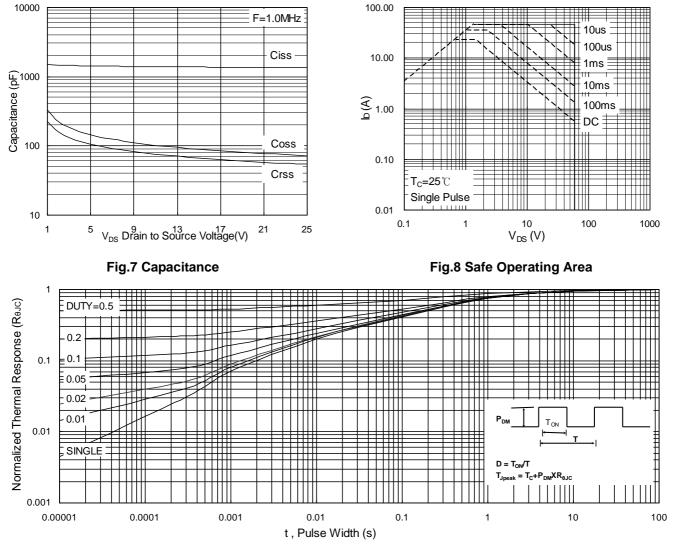


Fig.9 Normalized Maximum Transient Thermal Impedance

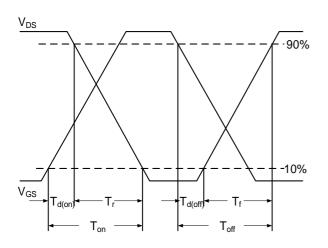
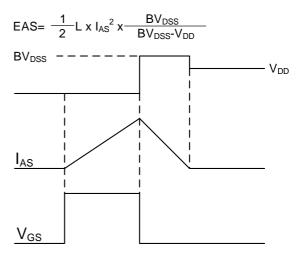


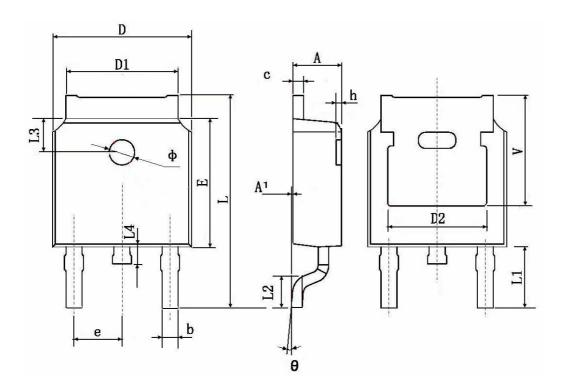
Fig.10 Switching Time Waveform







# TO-252-2L(TO-252-2(DPAK)) Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
A	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
с	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483	0.483 TYP. 0.190 TYP.		TYP.	
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600	TYP.	0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Φ	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350	TYP.	0.211 TYP.		



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